

Features

- Uses CRM(CQ) advanced SkyMOS4 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \times R_{DS(on)}$ product(FOM)
- Qualified according to JEDEC criteria

Applications

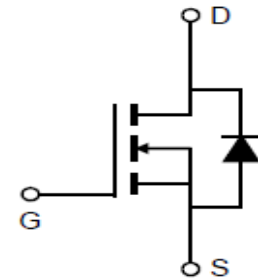
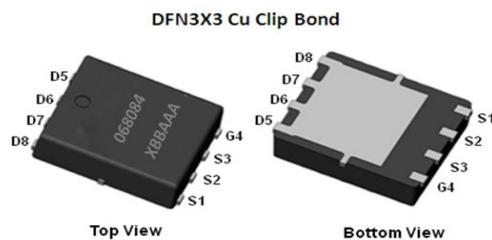
- Synchronous Rectification for AC/DC Quick Charger
- UPS (Uninterruptible Power Supplies)

Product Summary

V_{DS}	80V
$R_{DS(on)@10V typ}$	6mΩ
I_D	66A

100% Avalanche Tested

100% DVDS Tested



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRSK068N08N4	068084	DFN3333	Tape&Reel	N/A	N/A	5000pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	80	V
Continuous drain current $T_C = 25^\circ\text{C}$ (Silicon limit) $T_C = 25^\circ\text{C}$ (Package limit) $T_C = 100^\circ\text{C}$ (Silicon limit)	I_D	66 100 42	A
Pulsed drain current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	$I_{D pulse}$	265	A
Avalanche energy, single pulse ($L=0.3\text{mH}$, $R_g=25\Omega$)	E_{AS}	57	mJ
Gate-Source voltage	V_{GS}	± 20	V
Power dissipation ($T_C = 25^\circ\text{C}$)	P_{tot}	57	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+150	$^\circ\text{C}$
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	T_{sold}	260	$^\circ\text{C}$

※. Notes: 1. EAS is tested at starting $T_j = 25^\circ\text{C}$, $L = 0.3\text{mH}$, $I_{AS} = 17\text{A}$, $V_{GS} = 10\text{V}$.

Thermal Resistance

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	RthJC	-	1.7	2.2	°C/W	-
Thermal resistance, junction – ambient(min. footprint)	RthJA	-	35.2	53	°C/W	-

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV _{DSS}	80	-	-	V	V _{GS} =0V, I _D =250uA
Gate threshold voltage	V _{GS(th)}	2.2	3	3.8	V	V _{DS} =V _{GS} , I _D =250uA
Zero gate voltage drain current	I _{DSS}	-	-	1	μA	V _{DS} =80V, V _{GS} =0V T _j =25°C
		-	-	100		T _j =125°C
Gate-source leakage current	I _{GSS}		-	±100	nA	V _{GS} =±20V, V _{DS} =0V
Drain-source on-state resistance	R _{DS(on)}	-	6.0	7.2	mΩ	V _{GS} =10V, I _D =50A
		-	6.6	9.9	mΩ	V _{GS} =8V, I _D =40A
Transconductance	g _{fs}	-	90	-	S	V _{DS} =5V, I _D =50A

Dynamic Characteristic

Input Capacitance	C _{iss}	-	2093	4186	pF	V _{GS} =0V, V _{DS} =40V, f=1MHz
Output Capacitance	C _{oss}	-	539	1078		
Reverse Transfer Capacitance	C _{rss}	-	32	100		
Gate Total Charge	Q _G	-	30	45	nC	V _{GS} =10V, V _{DS} =40V, I _D =50A, f=1MHz
Gate-Source charge	Q _{gs}	-	11	20.0		
Gate-Drain charge	Q _{gd}	-	6.5	15		
Turn-on delay time	t _{d(on)}	-	13.6	-	ns	V _{GS} =10V, V _{DD} =40V, R _{G_ext} =2.7Ω
Rise time	t _r	-	79.2	-		
Turn-off delay time	t _{d(off)}	-	19.4	-		
Fall time	t _f	-	30	-		
Gate resistance	R _G	-	0.5	2	Ω	V _{GS} =0V, V _{DS} =0V, f=1MHz

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	0.9	1.4	V	$V_{GS}=0V, I_{SD}=50A$
Body Diode Continuous Forward Current	I_S	-	-	66	A	TC = 25°C
Body Diode Pulsed Current	I_S pulse	-	-	265	A	TC = 25°C
Body Diode Reverse Recovery Time	t_{rr}	-	45.8	91.6	ns	$I_F=50A, dI/dt=100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{rr}	-	67.8	135.6	nC	

Typical Performance Characteristics

Fig 1: Output Characteristics

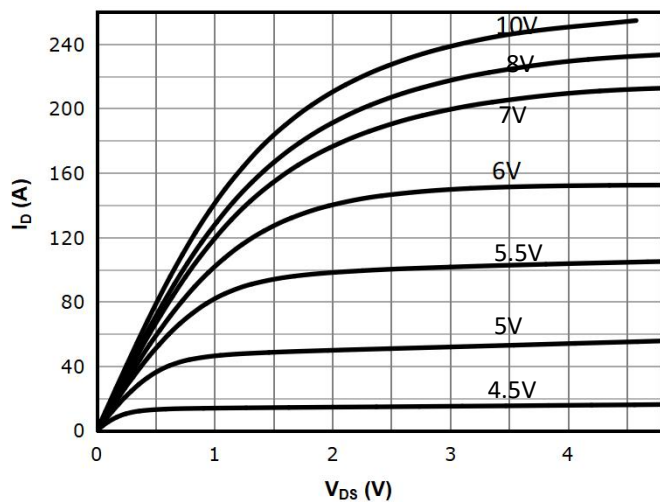
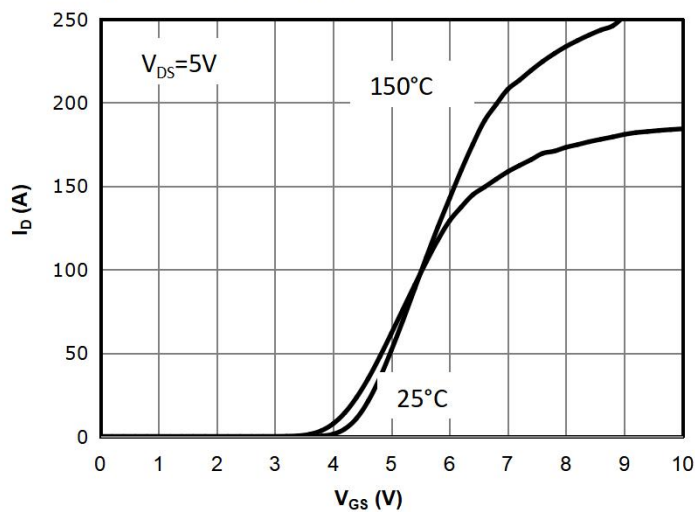


Fig 2: Transfer Characteristics



3: $R_{DS(on)}$ vs Drain Current and Gate Voltage

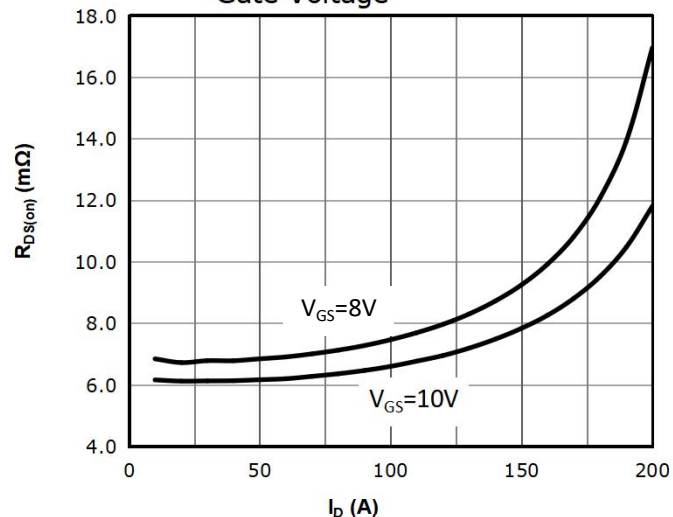


Fig 4: $R_{DS(on)}$ vs Gate Voltage

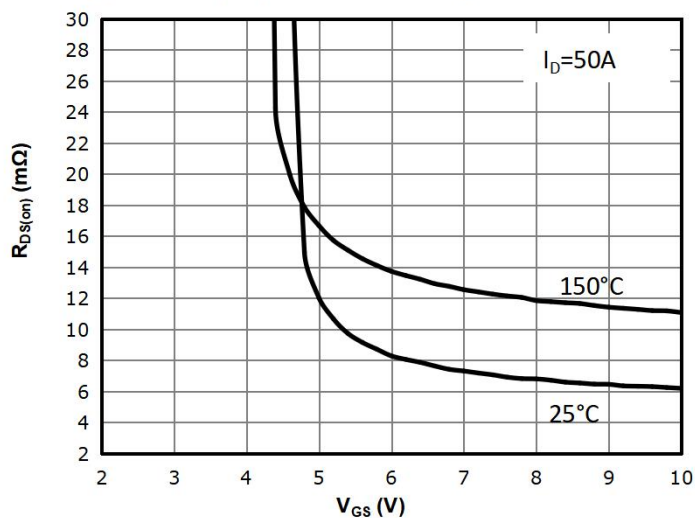


Fig 5: $R_{DS(on)}$ vs. Temperature

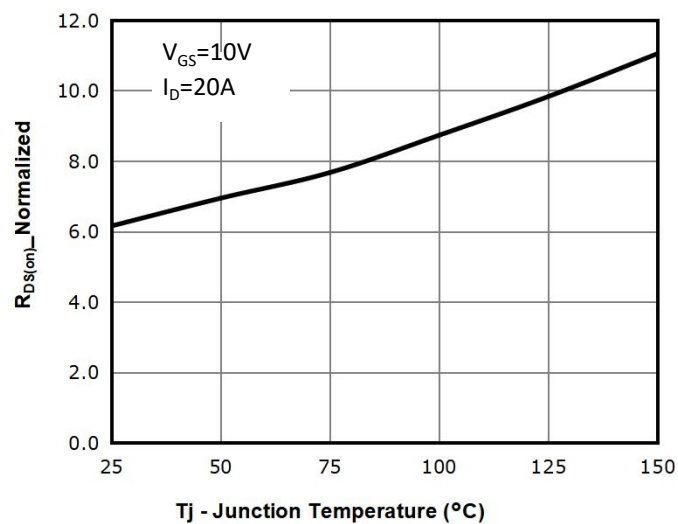


Fig 6: Capacitance Characteristics

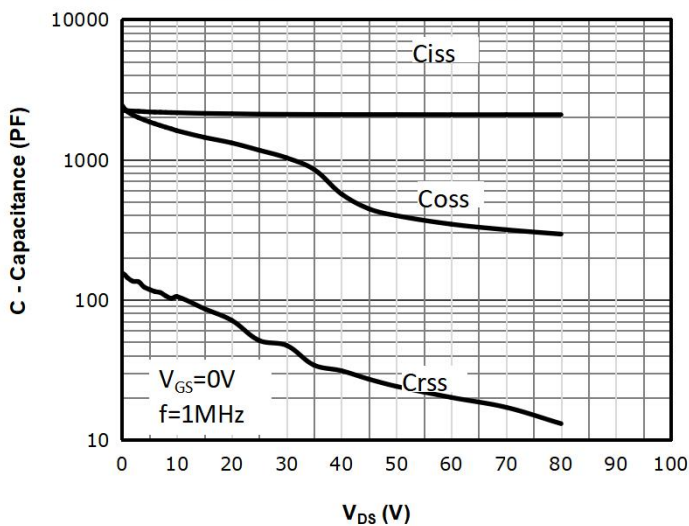


Fig 7: Gate Charge Characteristics

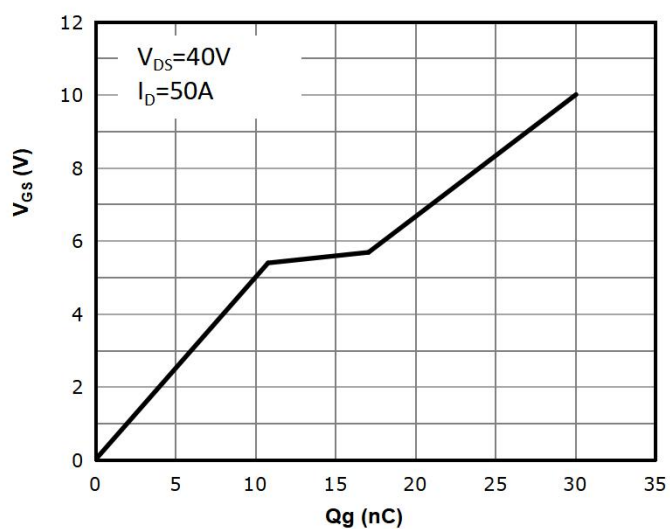


Fig 8: Body-diode Forward Characteristics

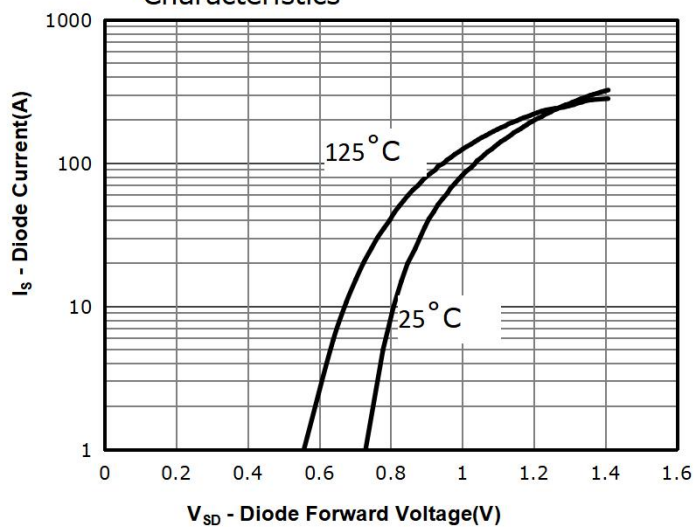


Fig 9: Power Dissipation

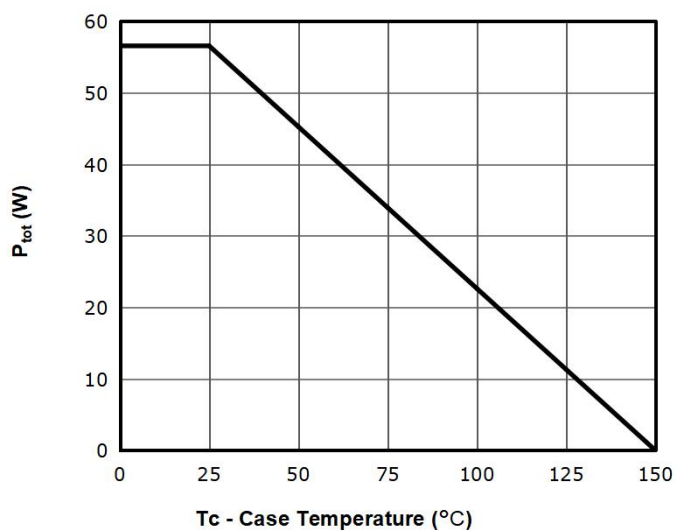


Fig 10: Drain Current Derating

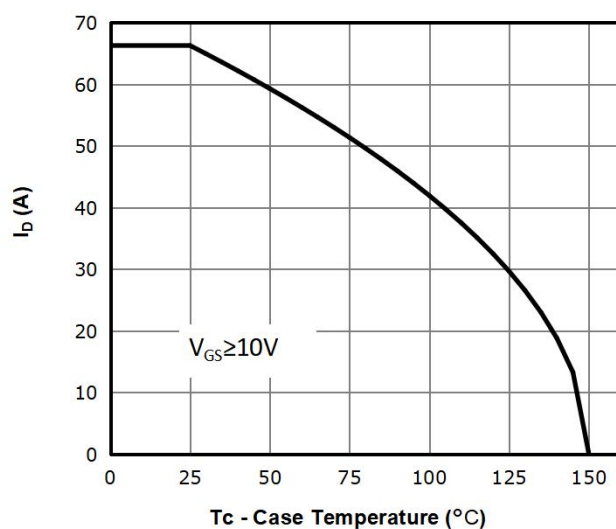


Fig 11: Safe Operating Area

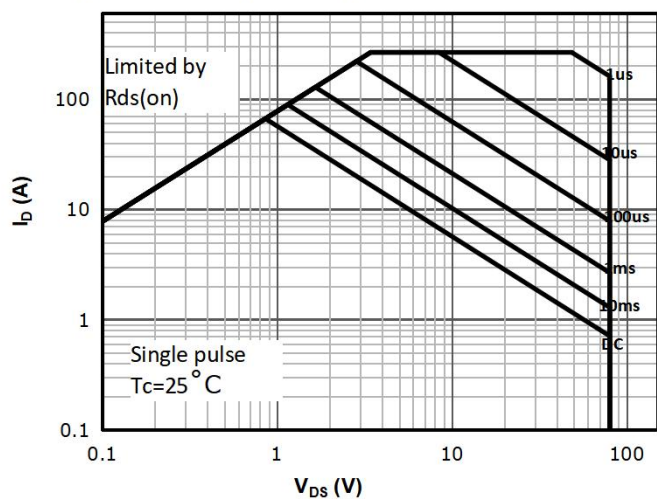
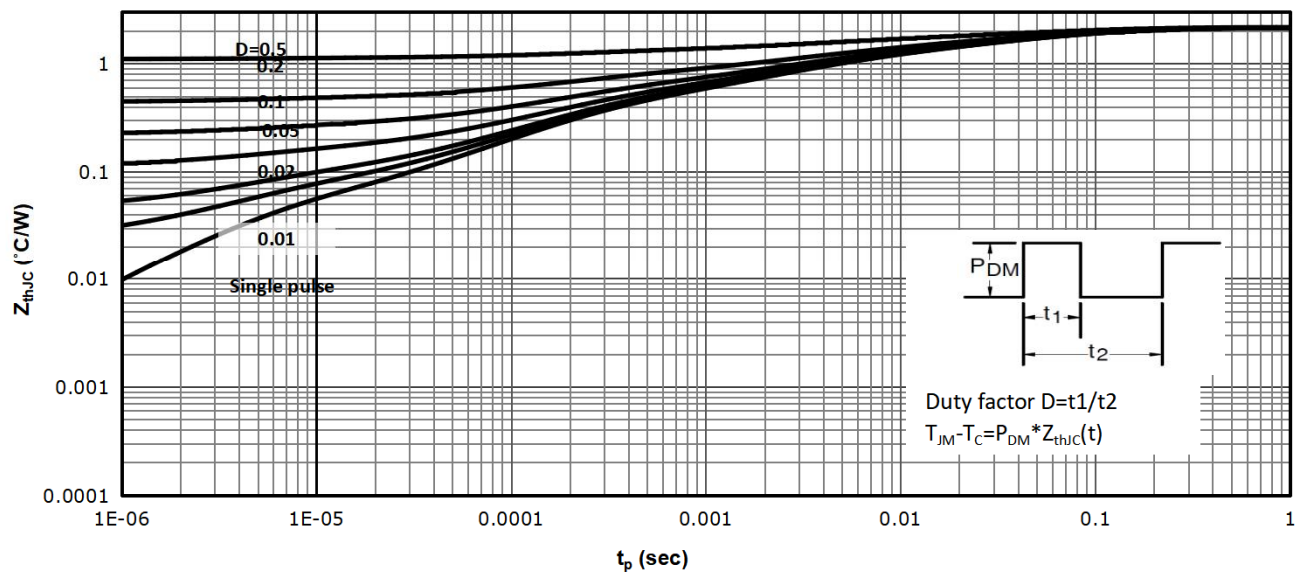
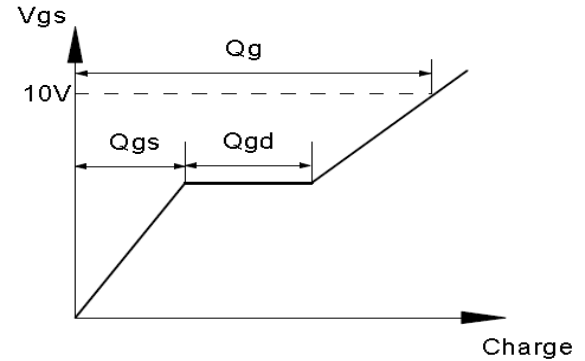
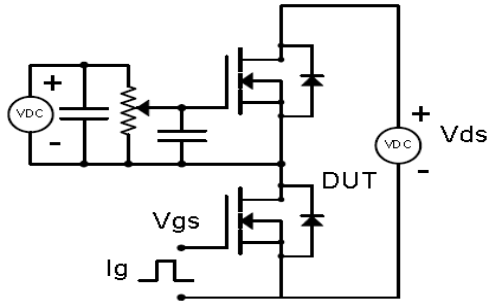


Fig 12: Max. Transient Thermal Impedance

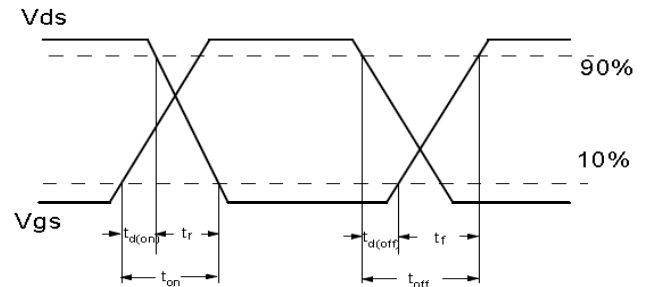
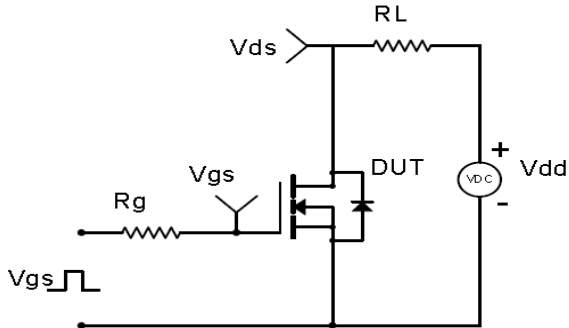


Test Circuit & Waveform

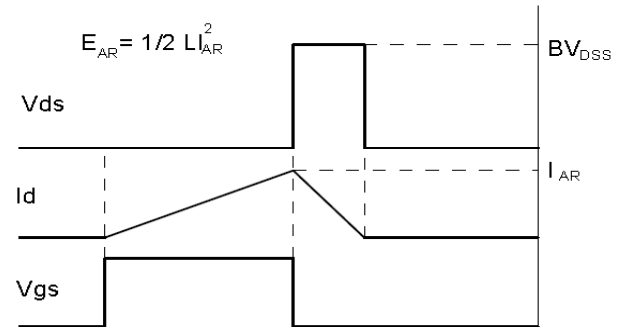
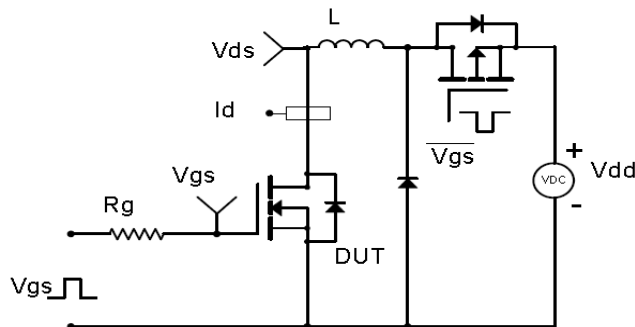
Gate Charge Test Circuit & Waveform



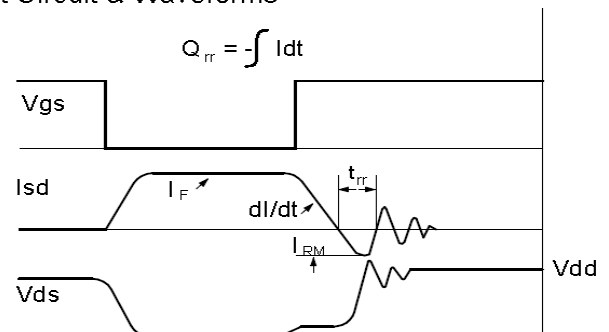
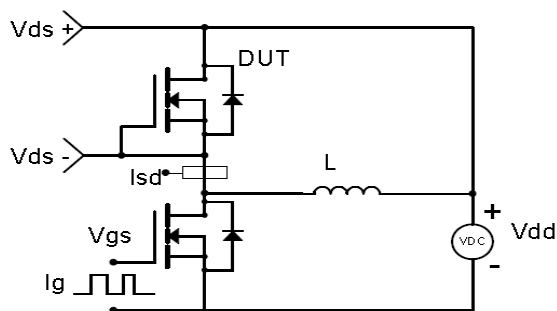
Resistive Switching Test Circuit & Waveforms



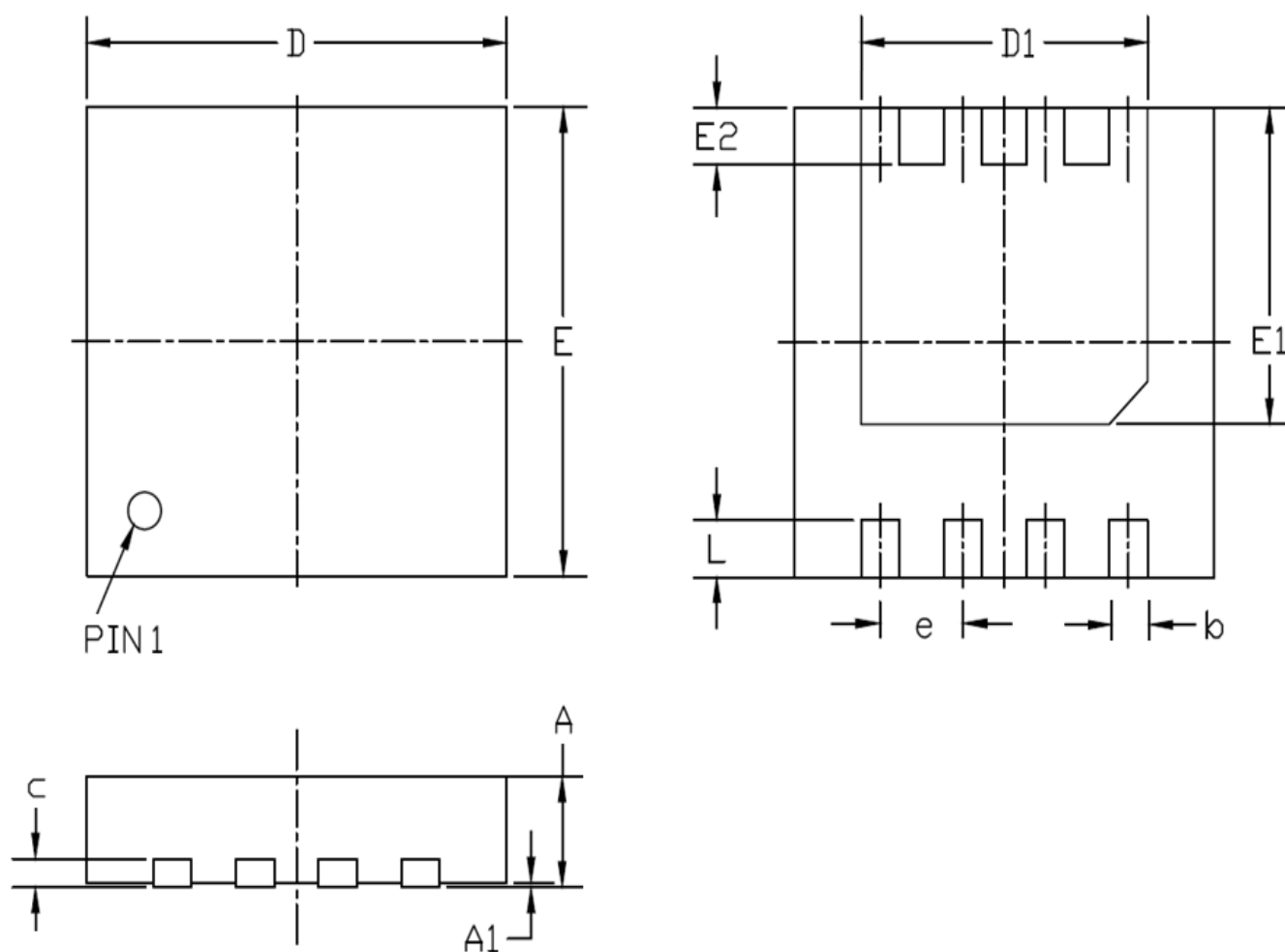
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

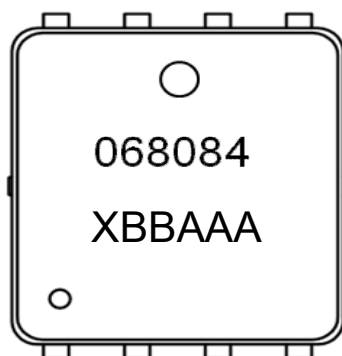


Package Outline: DFN3X3



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.70	0.85	0.028	0.033
A1	0.00	0.05	0.000	0.002
b	0.24	0.39	0.009	0.015
c	0.10	0.25	0.004	0.010
D	3.20	3.40	0.126	0.134
D1	2.15	2.39	0.085	0.094
E	3.20	3.40	0.126	0.134
E1	1.85	2.33	0.073	0.092
E2	0.25	0.50	0.010	0.020
e	0.65 BSC		0.026 BSC	
L	0.30	0.55	0.012	0.022

Marking



NOTE:
XBBAAA

X	—Assembly location code
BB	—Fab code
AAA	—Lot code

Revision History

Revision	Date	Major changes
1.0	2021/4/20	Release of Preliminary version.

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.